2025 OFC *First News*

Each year, OFC unites industry leaders, academia and government representatives from more than 80 countries across the globe, to participate in a comprehensive technical program and a sold-out exhibition showcasing the latest innovations driving the optical communication field forward.

With over 14,000 expected registrants and an exhibit hall packed with more than 670 exhibitors, OFC 2025 is an unparalleled gathering for industry professionals and the global hub for innovation and collaboration.

Topics such as 1.6 Terabit, AI, Coherent PON, Linear Pluggable Optics (LPO), multicore fiber, data center technology and quantum networking will capture the interest of our global audience facilitating the exploration of the latest advancements in optical communications and networking technology.

As OFC 2025 celebrates a historic half-century milestone—50 years of innovation, groundbreaking research, cutting-edge technological advancements and unmatched industry collaboration—we invite you to get a sneak peek at some of the news that our exhibitors will be sharing at the conference.

Acacia

Meeting Room 56

Release Date: 02/28/2025

Category: Pluggables

Acacia's Delphi-powered coherent optical modules have gained significant customer momentum with successful trials. Leveraging Acacia's 800G ZR+ pluggable with Interoperable Probabilistic Constellation Shaping, Colt Technology Services completed a 667km trial and Arelion achieved 1,069km transmission. Arelion also completed a groundbreaking 2,253km network field trial with Acacia's 400G Ultra-long haul module. Delphi is Acacia's 9th generation DSP and was honored with a 2025 Lightwave Innovation Review award. It leverages the deployment successes of its performance-optimized CIM 8 module to provide MSA pluggable products that offer increased capacity and longer reaches.

Contact: Kelly Karr, 978-996-5770, kelly@karrpr.com www.acacia-inc.com

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Aehr Test Systems

Booth 1857

Release Date: 03/13/2025

Category: Production Test Equipment

Aehr Test Systems (NASDAQ: AEHR), a worldwide supplier of semiconductor test and burn-in equipment, today announced it has received initial follow-on production orders totaling approximately $4.7 million from a major storage device supplier. The orders include multiple FOX-CPTM systems and proprietary WaferPakTM Contactors, which will be used for 100% test and burn-in of production devices in a new high-volume advanced storage application for the artificial intelligence (AI) enterprise and data center market

Contact: Jim Byers, 408 859-2995, jbyers@pondel.com, www.aehr.com

Albis Optoelectronics AG

Booth 1657
Release Date: 03/03/2025
Category: Photodetectors

Albis releases new 200G photodiode - Albis Optoelectronics releases its latest cutting-edge photodiode, designed to meet the demands of next-generation high speed optical communications. PD50Y1 is a compact 200G photodiode chip sporting an unsurpassed responsivity, targeting next-gen optical transceivers in data centers and telecom applications. This photodiode features an integrated backside lens for easy and efficient optical coupling, and supports up to 200 Gbps per channel, ensuring superior data transmission speeds. The chip topside pads are optimized for flip-chip soldering processes using AuSn or SAC305.

Contact: Mayra Irion, 41-44-5525300, mayra.irion@albisopto.com, www.albisopto.com

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Albis Optoelectronics AG

Booth 1657
Release Date: 03/07/2025
Category: Photodetectors

Albis announces new photodiode for 400G - At the upcoming OFC Exhibition 2025, Albis Optoelectronics will be showcasing its new PD80X1 photodiode chip, designed for advanced 400G per lane applications. This chip is ideal for high-density, high-bandwidth applications, making it a perfect fit for future-proof optical networks. It offers ultra-fast data transfer, high-density integration, and energy efficiency, supporting the growth of cloud computing, AI, and IoT technologies. The advanced design supports seamless integration into existing systems, providing customers with a robust solution for their evolving network needs.

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Aloe Semiconductor, Inc

Booth 1018

Release Date: 03/04/2025

Category: Optical Transmitters/Receivers

Aloe Semiconductor, Inc. (Aloe), a semiconductor design company specializing in advanced silicon-photonic integrated circuits (PICs), will demonstrate its latest dual-polarization and high-baud-rate silicon photonics technologies at OFC this spring. These high-performing technologies reduce cost, size, and power and can be integrated into existing networks, enabling scalability of up to 850Gb per lane. This demonstration will showcase Aloe's mission of creating radically new silicon photonics and electronics solutions for next-generation optical communications.

Contact: Hanako Doerr, 732-216-6441, hdoerr@aloesemi.com, www.aloesemi.com

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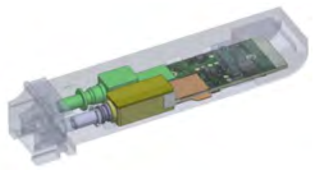
Bifrost Communications

Booth 4952

Release Date: 03/17/2025

Category: Quasi-Coherent Networking

Bifrost announces the launch and demonstration of its 25Gbps 40 km reach transceiver solution. A live demonstration of a 25Gbps transceiver package with 40 km reach will take place at the Bifrost booth 4952 from April 1 to April 3. The 25Gbps solution provides an easy upgrade of existing Access networks from 10Gbps to 25Gbps and is based on Bifrost's proprietary Quasi Coherent transceiver technology. Bifrost Communications is sharing their booth with the ESTEL Optical Transceiver Production Company from Belgium. The ESTEL European facility is currently the only fully European Transceiver production line producing high-quality optical transceivers. ESTEL will be co-developing and producing the full range of Bifrost Quasi Coherent transceivers.



Contact: Anders Terkildsen, 45-40-33-4636, at@bifrostcommunications.com, www.bifrostcommunications.com

Bola Technologies

Booth 5115
Release Date: 03/11/2025
Category: Production Test Equipment

Bola Technologies, a global fiber optic testing and measurement equipment manufacturer, announced it has added extended L-band capability (186.0 THz to 190.95 THz) to its established extended C-band Dynamic Optical Filter Array (DOFA) platform available exclusively through OgMentum. This enhancement provides customers with increased wavelength range, enabling more optical testing amid the proliferation of AI/ML and other bandwidth-consumptive applications. Bola's extended C- and L-band DOFA platform will be showcased at the Optical Fiber Communications Conference and Exhibition (OFC) in San Francisco, California, from April 1-3 at OgMentum Booth #5115, along with other high-performance solutions from Bola Technologies, FiberLabs Inc., SYCATUS and PFO Instruments.

Contac: Sydney Drayton, 510-295-4972, sdrayton@engagepr.com, www.bolatech.com

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Casela Technologies

Booth 6549
Release Date: 03/12/2025
Category: Lasers - Other

Casela Technologies, a leader in high-power, efficient DFB lasers, will showcase their family of Dual and Quad Laser Source Assemblies (LSAs) at OFC 2025. These packaged lasers provide an external, easy to integrate CW laser source, optimized for multi-channel 1.6 and 3.2Tb silicon photonic transceivers. Casela, will have a live demonstration of the Quad LSA with over 150mW per fiber. LSAs are available uncooled or with thermal control via an integrated TEC. The Dual/Quad LSA integrates 2/4 high power CW-DFB lasers in a compact package. The lasers are PM fiber-coupled with an integrated isolator. Efficient, high-power CW-DFB lasers are available in O, C and L bands. Casela supports DRx, CWDM and DWDM channels with 200GHz spacing.

Contact: Tim Munks, 860-970-8868, tim.munks@caselatech.com, www.caselatech.com

Casela Technologies

Booth 6549
Release Date: 03/12/2025
Category: Lasers - Other

Casela Technologies, a leader in high-power, efficient DFB lasers, will showcase ELSA-16, their new family of compact, External Laser Source Assemblies. ELSA-16 is a CW laser platform optimized for high bandwidth silicon photonic transceivers used in scale-up AI and CPO architectures. Casela's ELSA-16 integrates 16 high-power DFB lasers with control electronics and software. Lasers are individually isolated and PM fiber-coupled. The electronics and software support CMIS and the electrical I/O is via a QSFP-DD connector. The ELSA-16 is available in O, C and L band and supports DRx, CWDM and DWDM channels with 200GHz spacing.

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Ethernet Alliance

Booth 5173
Release Date: 02/26/2025
Category: High Speed Technology and Data Formats

The Ethernet Alliance interoperability demonstration at OFC 2025 will showcase the evolution of 800G products including new interconnect schemes, interoperating within a representative network. The demo will feature the multitude of speeds found in a datacenter closet, from 100G to 800G, connected over the latest in current and emerging passive and active copper and optical interfaces. There will be solutions from a wide range of ecosystem participants, including test & measurement, interconnect, systems, and switches. The interoperability demos offer attendees a chance to see state-of-the-art networking technologies operating in a real-world setting.

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Finetech

Booth 6367
Release Date: 03/01/2025
Category: Manufacturing/Automation/Packaging Equip. & Materials

Finetech proudly introduces the FINEPLACER® femto pro, the next generation in automated multi-purpose bonding technology. Engineered for high-yield and sustainable mid-volume production, this fully automatic system achieves a placement accuracy of 2.0 µm @ 3 Sigma and supports ultra-low to high bonding forces. With compatibility for a wide range of die attach technologies—including laser-assisted bonding, ultrasonic bonding, adhesive bonding, thermo-compression, eutectic, and reactive soldering—the FINEPLACER® femto pro is a powerful solution for cutting-edge assembly processes.

Contact: Steve Breed, 617-335-1570, SBreed@finetechusa.com, www.finetechusa.com

FormFactor

Booth 6249
Release Date: 03/17/2025
Category: Production Test Equipment

FormFactor introduces TRITON, the first production silicon photonics test system designed for high-throughput manufacturing environments. Key features include high-volume manufacturing testing with SECS/GEM, OHT and automated probe card changer compatibility. The system also offers surface and edge coupling compatibility as well as probe card integration with FAU for both optical and electrical measurements. Developed in partnership with Advantest and TEL, the system will be available for purchase in Q3 2025. FormFactor ensures full system connectivity.

Contact: Carole Garner, 541-815-7790, carole.garner@formfactor.com, www.formfactor.com

Fujitsu

Booth 1431

Release Date: 03/03/2025

Category: Pluggables

Fujitsu unveils the 1FINITY™ P300 800G ZR/ZR+ coherent pluggable transceiver, an open, high-performance solution to optimize performance, cost, and power consumption for sustainable optical transport networking. Data demands of AI and cloud are driving the need for greater speed, capacity and flexibility throughout telecommunications and data center networks. The 1FINITY P300 enables next-generation data center interconnect, metro, regional, and long-haul transport network owners to address these challenges sustainably and cost-effectively. Featuring the latest 3nm DSP semiconductor and support built-in to Virtuora network control, the transceivers enable high performance with 30% power per bit reduction and lower costs versus previous generations.

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HieFo Corporation

Booth 6478

Release Date: 03/10/2025

Category: Lasers - Communications

HieFo is set to unveil transformative optical chip innovations at OFC 2025. Highlights include InP-based DFB lasers with up to 150 mW output and 50 kHz linewidths, ideal for coherent transmission. The high-power gain chip boosts efficiency by 40%, supporting outputs up to 22 dBm. HieFo's latest CW laser chip addresses IMDD applications, integrating seamlessly with Silicon Photonics transceivers for data centers. Additionally, HieFo introduces a revolutionary PDK, streamlining InP photonic design. With multiple IP applications filed, HieFo is driving photonics forward. Meet us at OFC to explore these disruptive technologies and learn more about our innovative solutions.

Contact: Veronica Cai, 626-561-8725, Veronica_cai@hiefo.com, www.hiefo.com

HYC Co., Ltd

Booth 3020
Release Date: 03/17/2025
Category: Co-packaged Optics

Optical Interconnection Solutions for Co-packaged Optics (CPO). With over 20 years of expertise, HYC offers customizable solutions—from fiber flexible optical shuffle to PM assemblies—tailored for front-panel, on-board, and back-panel connections in CPO switches. Fiber flex circuits for on-board connections: Up to 1000+ fibers in one circuit. Enable automated fiber routing and cabling, optimized for high-volume production scalability. MPO/MTP assemblies for front panel connections: Precision mold design and advanced injection molding capabilities, made in Thailand, large capacity. Polarization-Maintaining (PM) assemblies between ELS and OE: With mature process technologies and automated production capabilities for key processes, HYC ensures large-scale supply and consistency of PM products. Photonic Integrated Circuit (PIC) connections: Equipped with space optics design capabilities, precision back-end processing and optical analysis capabilities.

Contact: Bella Tse, bella@hyc-system.com, www.hyc-system.com

MRSI Mycronic

Booth 3218
Release Date: 01/27/2025
Category: Manufacturing/Automation/Packaging Equip. & Materials

MRSI Mycronic announces advanced high-speed 1µm die bonder MRSI-LEAP for ultra-high-volume manufacturing of AI optical module applications MRSI Mycronic is proud to announce the launch of the MRSI-LEAP high-speed 1µm die bonder. This innovative equipment is designed for ultra-high-volume manufacturing of optical modules, including Chip-on-Carrier (CoC), Chip-on-Submount (CoS), and Chip-on-Board (CoB) assemblies utilizing epoxy processes. The MRSI-LEAP high-speed 1µm die bonder boasts a range of innovative features that make it an essential tool for ultra-high-volume manufacturing. It offers unparalleled efficiency with exceptional precision <±1µm @ 3σ ensuring long-term stability and high precision in true 24/7 die bonding applications to support ultra-high volume driven by AI.

Contact: Jennifer Russo, 978-667-9449, jennifer.russo@mycronic.com, www.mycronic.com

NLM Photonics

Booth 6383

Release Date: 03/04/2025

Category: Integrated Photonics

NLM Photonics, a leader in hybrid organic electro-optic (OEO) technology, and CoMotion at the University of Washington (UW) announce the awarding of a patent covering a new thermoset hybrid OEO material, developed in the research labs of Professors Bruce Robinson and Larry Dalton in the UW Department of Chemistry. Known as Selerion-HTX™ commercially and HLD in scientific literature, this material redefines the boundaries of photonic performance, balancing a high EO coefficient (r33) and index of refraction with unprecedented long-term temperature stability for a hybrid OEO material. Selerion-HTX is the first material in NLM's Selerion family of hybrid OEO technologies.

Contact: Theo McGillivray, 206-413-9987, theom@nlmphotonics.com, www.nlmphotonics.com

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OIF

Booth 5745

Release Date: 03/12/2025

Category: Interoperability

OIF is advancing interoperability at OFC 2025 with live demos, expert insights, and cross-industry collaboration. From April 1-3 in San Francisco, 35 members will showcase seamless multi-vendor integration for AI, cloud, and disaggregated architectures. Highlights include 800G pluggable coherent optics, a live Common Electrical I/O (CEI)-448G, 224G, and 112G demonstration, Common Management Interface Specification (CMIS) plug-and-play interoperability, and Energy Efficient Interfaces (EEI) with co-packaging solutions for AI compute and external laser integration. OIF will also lead expert panels on AI networking, optical interconnects, scalable architectures, and next-gen signaling beyond 200 Gb/s.

Contact: Leah Wilkinson, 703-307-3964, leah@wilkinson.associates, www.oiforum.com

OpenLight

Booth 4231
Release Date: 03/14/2025
Category: Integrated Photonics

OpenLight, the world leader in custom PASIC chip design and manufacturing, will showcase its latest developments in photonic solutions and partner demos at OFC 2025 to support next-gen communication architectures. OpenLight's demonstrations will feature its first heterogeneously integrated silicon photonics-based 1.6Tb DR8 PICs, utilizing DFB lasers and 200G EAM modulators and a demo of OpenLight's cutting-edge 400G/lane electro absorption modulator. For more detailed information, please visit OpenLight at booth #4231 on 1-3 April 2025.

Contact: Rachel Yang, 360-910-5860, rachely@hoffman.com, www.openlightphotonics.com

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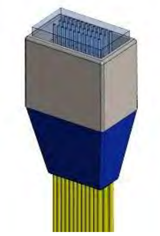
OZ Optics Ltd.

Booth 2018
Release Date: 02/12/2025
Category: Fiber Cables, Assemblies



OZ Optics, a recognized leader in high-performance optical fiber components and subsystem module assemblies, has launched its new line of 2D-Fiber Array (FA) assemblies. Building on its extensive experience with 1D V-Groove FA, OZ now offers an advanced 2D-FA solution to meet the growing demand for higher-density optical transmission for a variety of applications, including optical cross-connection, biomedical imaging, spectroscopy, and astronomy. The 2D-FAs are available in PM, SM, and MM Fiber configurations, with custom fibers, wavelengths, and optical specifications with a range of termination options, including high-precision MPO/MTP® termination, providing optimal performance and ease of integration into existing systems.

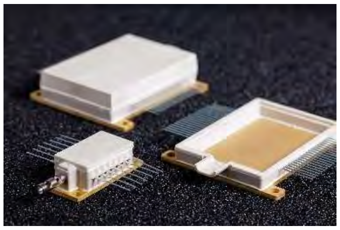
Contact: Yesim Sezerman, 613-831-0981, ysezerman@ozoptics.com, www.ozoptics.com

PHIX Photonics Assembly

Booth 6266

Release Date: 03/10/2025

Category: Manufacturing/Automation/Packaging Equip. & Materials



In partnership with RJR Technologies PHIX offers LCP air cavity packages for integrated photonics. At high manufacturing volumes this packaging solution combines a low cost per unit with low packaging costs, by enabling multi-device strip-level assembly on lead frames.

Contact: Gijs van Ouwerkerk, 31-88-7449009, marketing@phix.com, www.phix.com

Sumix

Booth 3021

Release Date: 03/08/2025

Category: Production Test Equipment

Sumix Launches Glide MT: A Robotic Microscope Simplifying MIL-DTL-38999 Inspections Sumix introduces the Glide MT, a cutting-edge robotic microscope designed for automated inspection of MIL-DTL-38999 connectors. Equipped with an XYZ motion system, it seamlessly inspects multiple MT end faces in a programmed sequence, detecting scratches, defects, and contamination with MaxInspect™ software. Its versatile design allows for inspection of both plugs and receptacles, making it optimal for production, field maintenance, and troubleshooting. The Glide MT eliminates the need for manual inspection of each ferrule, automating the process for faster and more consistent results. For more details, visit www.sumix.com or contact info-team@sumix.com.

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